

CATEGORY	DESCRIPTION	P/N #
CONNECTOR	Modular Jack, 10P8C, 1X2PORT	MJ5908-BX12-BRF4

REV.	ECN NO	DESCRIPTION	REVISED	DATE
A01		New Release	Kelly	2008.05.22

**NOTES:**

**MATERIAL:**

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER(UL94V-0).
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE  $\phi 0.46\text{mm}$  (C5100).
- 3.PLATING :GOLD PLATING OVER NICKEL.
- 4.SHIELD: COPPER ALLOY 0.20mm THICKNESS PLATING NI.

**ELECTRICAL:**

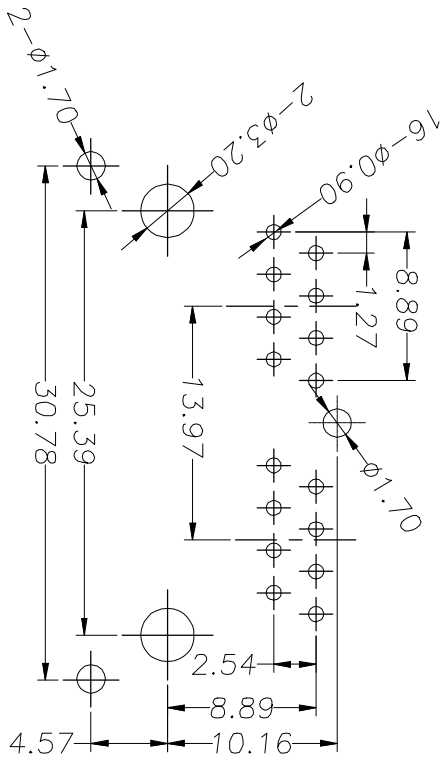
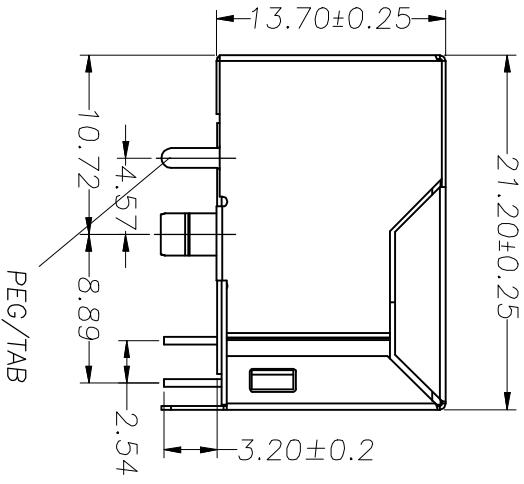
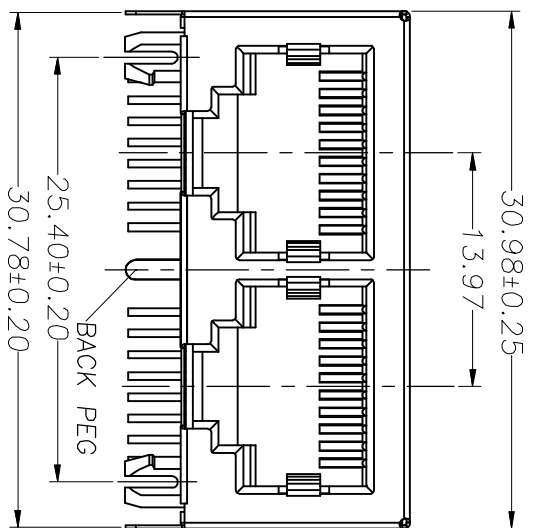
- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :50 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC.
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50HZ. 1MIN.

**MECHANICAL:**

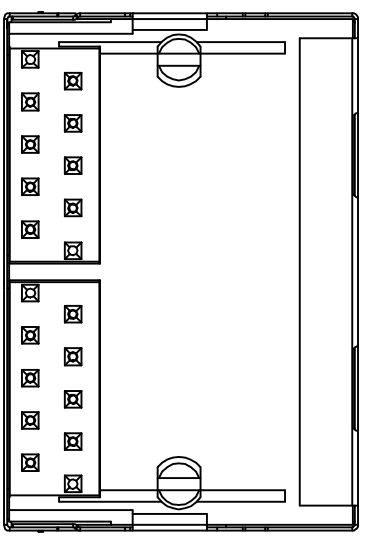
- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

**ENVIRONMENTAL:**

- 1.STORAGE : -40°C TO +85°C.
  2. OPERATION : 0°C TO 70°C.
- MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68,SUBPART F.



PC Board Layout



Part No.: MJ5908-BX12-BRF4

Table 1

	Material & Plating
X	Terminal Plating
0	Au 1u" Plating
1	Au 3u" Plating
2	Au 6u" Plating
3	Au 15u" Plating
4	Au 30u" Plating
5	Au 50u" Plating

**Product Drawing**  
Dongguan Hejing Electronic Co.,LTD

UNLESS OTHERWISE SPECIFIED TOLERANCES	SCALE:1/1	UNIT: mm	DWG.NO:	WI-061-751
DECIMALS: X ±0.5	ANGLES: X ±2°	SIZE: A3	APPROVED BY	PREPARED BY
X.X ±0.3	X.X ±.1°	PAGE:1 OF 1	Bill	Kelly
X.XX ±0.2		REV:A01	CHECKED BY	
			Bill	
			APPROVED BY	
			Tony	

CUSTOMER COPY